

inorganic surface modification coatings, specified in column 3 of the following Table;
 - To non-electronic substrates, specified in column 2 of the following Table;
 - By processes specified in column 1 of the following Table and defined in the Technical Note;

TABLE - DEPOSITION TECHNIQUES

1. Coating Process (1)*	2. Substrate	3. Resultant Coating	
A. Chemical Vapour Deposition (CVD)	"Superalloys"	Aluminides for internal passages	
	Ceramics and Low-expansion glasses (14)	Silicides Carbides Dielectric layers (15)	
	Carbon-carbon, Ceramic and Metal "matrix" "composites"	Silicides Carbides Refractory metals Mixtures thereof (4) Dielectric layers (15) Aluminides Alloyed aluminides (2)	
	Cemented tungsten carbide (16), Silicon carbide	Carbides Tungsten Mixtures thereof (4) Dielectric layers (15)	
	Molybdenum and Molybdenum alloys	Dielectric layers (15)	
	Beryllium and Beryllium alloys	Dielectric layers (15)	
	Sensor window materials (9)	Dielectric layers (15)	
	B. Thermal-Evaporation Physical Vapour Deposition (TE-PVD)	"Superalloys"	Alloyed silicides Alloyed aluminides (2) MCrAlX (5) Modified zirconia (12) Silicides Aluminides Mixtures thereof (4) Dielectric layers (15)
			Ceramics and Low-expansion glasses (14)
			Corrosion resistant steel (7)
Carbon-carbon, Ceramic and Metal "matrix" "composites"			
Cemented tungsten carbide (16), Silicon carbide			
Molybdenum and Molybdenum alloys			
Beryllium and Beryllium alloys			
Sensor window materials (9)			
Titanium alloys (13)			
Borides Nitrides			
B.1. Physical Vapour Deposition (PVD): Electron-Beam (EB-PVD)	"Superalloys"	Alloyed silicides Alloyed aluminides (2) MCrAlX (5) Modified zirconia (12) Mixtures thereof (4) Dielectric layers (15)	
		Ceramics and Low-expansion glasses (14)	
		Corrosion resistant steel (7)	
		Carbon-carbon, Ceramic and Metal "matrix" "composites"	
		Cemented tungsten carbide (16), Silicon carbide	
		Molybdenum and Molybdenum alloys	
		Beryllium and Beryllium alloys	
		Sensor window materials (9)	
		Titanium alloys (13)	
		Borides Nitrides	

TABLE - DEPOSITION TECHNIQUES

1. Coating Process (1)*	2. Substrate	3. Resultant Coating
B.2. Ion assisted resistive heating Physical Vapour Deposition (Ion Plating)	Ceramics and Low-expansion glasses (14)	Dielectric layers (15)
	Carbon-carbon, Ceramic and Metal "matrix" "composites"	Dielectric layers (15)
	Cemented tungsten carbide (16), Silicon carbide	Dielectric layers (15)
	Molybdenum and Molybdenum alloys	Dielectric layers (15)
	Beryllium and Beryllium alloys	Dielectric layers (15)
	Sensor window materials (9)	Dielectric layers (15)
B.3. Physical Vapour Deposition: "laser" evaporation	Ceramics and Low-expansion glasses (14)	Silicides Dielectric layers (15)
	Carbon-carbon, Ceramic and Metal "matrix" "composites"	Dielectric layers (15)
	Cemented tungsten carbide (16), Silicon carbide	Dielectric layers (15)
	Molybdenum and Molybdenum alloys	Dielectric layers (15)
	Beryllium and Beryllium alloys	Dielectric layers (15)
	Sensor window materials (9)	Dielectric layers (15) Diamond-like carbon
B.4. Physical Vapour Deposition: cathodic arc discharge	"Superalloys"	Alloyed silicides Alloyed aluminides (2) MCrAlX (5)
	Polymers (11) and Organic "matrix" "composites"	Borides Carbides Nitrides
C. Pack cementation (see A above for out-of-pack cementation) (10)	Carbon-carbon, Ceramic and Metal "matrix" "composites"	Silicides Carbides Mixtures thereof (4)
	Titanium alloys (13)	Silicides Aluminides Alloyed aluminides (2)
	Refractory metals and alloys (8)	Silicides Oxides
D. Plasma spraying	"Superalloys"	MCrAlX (5) Modified zirconia (12) Mixtures thereof (4) Abradable Nickel-Graphite Abradable Ni-Cr-Al-Bentonite Abradable Al-Si-Polyester Alloyed aluminides (2)

* The numbers in parenthesis refer to the Notes following this Table.